

Solvent soluble Polyimide varnish

Introduction of Q-AD-X0516

Application : 2Layer Flexible Copper-Clad Laminate, etc.

1-1) Outline

1. Outline and Feature

1-2) Feature and General properties

This is a varnish made from polyimide resin by dissolving in a solvent. Using this varnish, polyimide is available by just removing the solvent. In addition, this varnish can be used as a TPI layer for laminate double-layer FCCL because it has remarkable adhesiveness with polyimide film and VLP copper foil as well as high flexibility.

Item	Unit	Properties	Remark
Solvent	-	NMP	N-methyl-2-pyrrolidone Methyl benzoate
		BAME	
Solid contents	%	10	240°C×30min
Viscosity	cp	15,000	at 25°C
Specific gravity	-	1.32	at 25°C

1-3) Preservation stability

This can be stored at room temperatures. This varnish can be stored for a prolonged period of time because it has less time-dependent change in viscosity as compared with typical polyimide varnishes. However, please store it with airtight stopper because it easily absorbs damp.

1-4) Soluble Solvent

It shows high solubility in NMP and BAME. Please use it after adjusting its solid content and viscosity as desired.



2. Usage

How to make Polyimide film for Laminate-FCCL

Coating Q-AD-X0516 on Base-PI-film (Spin coating, Bar coating, etc.) → Drying (Hot air, IR, etc.)

120°C×1~5min+150°C×1~5min+180°C×1~5min+210°C×1~5min+240°C×1~5min

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Dry condition depends on coating thickness.

3. Properties

Item	Unit	Properties	Remark
Tg	°C	220	TMA
CTE	ppm	49	50~200°C
Thermal decomposition temp.	°C	490	Td2
Chemical resistance	%	-0.03	Weight loss by NaOH(40g/L,60°C×15min)

Measuring sample : 25umt TPI-film

4. Contact

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The Ultra-high heat resistant resin with
unlimited potential